

GRF5236

HIGH GAIN LINEAR DRIVER

3.1 to 4.2 GHz

RELEASE Ø DATA SHEET

FEATURES

- 1 dB Typical Gain Flatness (3.3 to 4.2 GHz) with a Single Tune
- Excellent Linearity Performance Over Wide Bandwidths
- Flexible Biasing Provides Latitude for Linearity Optimization
- 105 mA Native Mode Quiescent Current Consumption
- 50 Ω Single-ended Input and Output Impedances
- -40 to 115 $^{\circ}\text{C}$ Operating Temperature Range
- Compact 3 x 3 mm QFN-16 Package

Reference: 5 V / 95 mA / 3.8 GHz

- Gain: 36.7 dB
- OP1dB: 30.1 dBm
- OIP3: 33.8 dBm
- NF: 4.1 dB

APPLICATIONS

- Linear Driver / Pre-Driver Amplifiers
- 5G Sub-6 GHz Massive MIMO Base Stations
- Small Cells and Cellular Repeaters
- Millimeter Wave IF Stages
- High-Performance RF Infrastructure

ORDERING INFORMATION

Buy it Now

DESCRIPTION

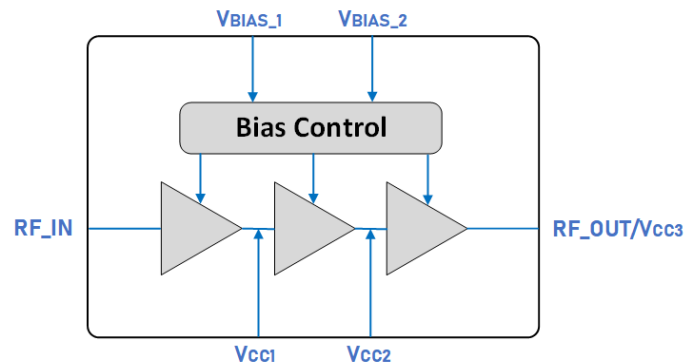
The GRF5236 is a high-gain, three-stage driver amplifier targeting 3.3 to 4.2 GHz wireless infrastructure applications. The device delivers up to 30.1 dBm of OP1dB, 33.8 dBm of OIP3, and a low noise figure (NF) of less than 4.1 dB over its targeted band of operation. OP1dB can be tuned down to 3.1 GHz, but the high frequency of the rated operating range will degrade.

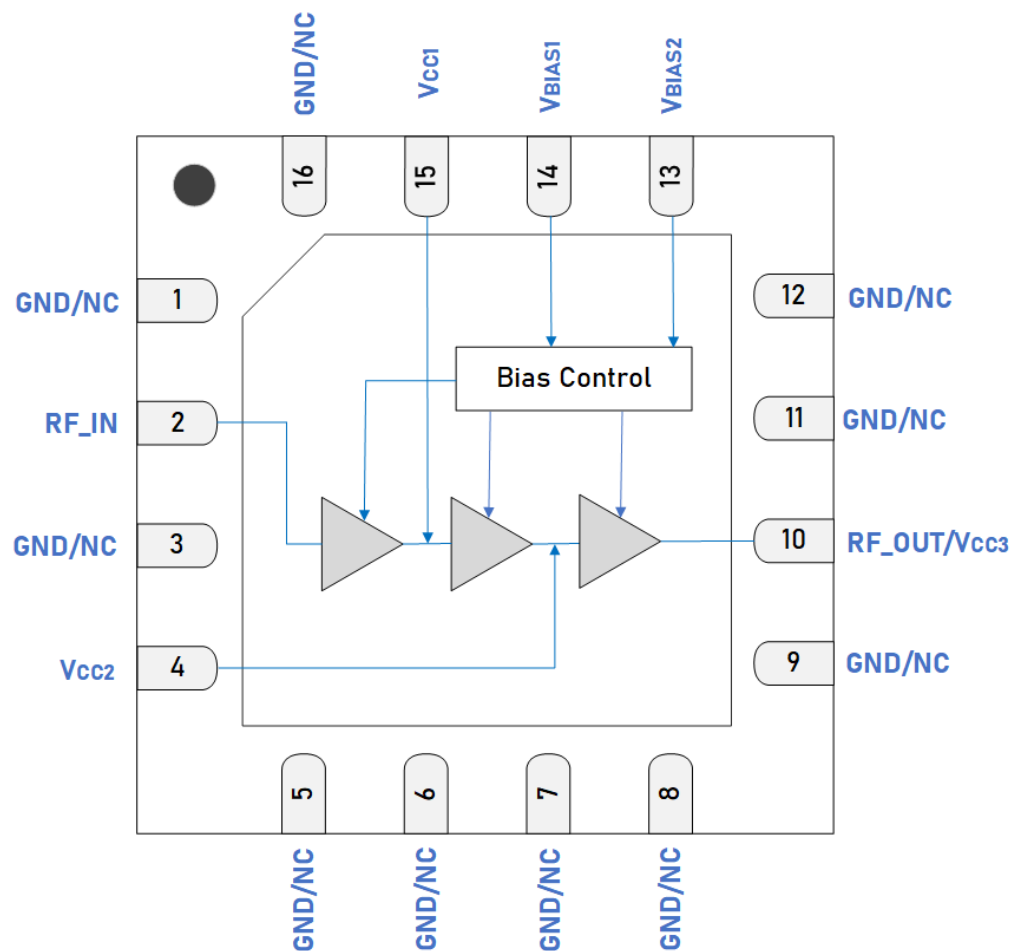
For optimal efficiency and linearity, the amplifier was designed to operate with a single 5 V supply voltage while using only 85-105 mA of quiescent current. 3.3 V supplies can also be used while still yielding 26.3 dBm of OP1dB. If desired, ICCQ can be increased beyond the native biasing point for enhanced linearity performance.

The GRF5236 is designed for 50 Ω systems, typically needing only a two-element shunt-series match on the output port.

Additional tunes can be found on the GRF5236 "Custom Tunes" product page: [GRF5236 Custom Tunes](#)

BLOCK DIAGRAM





Pin Assignments

Pin	Name	Description	Note
2	RF_IN	RF Input	The RF input is fully matched to 50 Ω , and it contains internal DC blocking capacitor.
1, 3, 5, 6, 7, 8, 9, 11,12, 16	GND/NC	Ground or No Connect	No internal connection. These pins can be left unconnected or connected to ground (recommended). Use a via as close to the pin as possible if grounded.
4	V _{CC2}	V _{CC} Bias Voltage	Pull up to V _{CC} through inductor and use bypass capacitors as close to the pin as possible. In addition to supplying the device with a DC voltage, there is also an RF signal present.
10	RF_OUT/V _{CC3}	RF Output/V _{CC3} Bias Voltage	V _{CC} must be applied through a choke to this pin.
13	V _{BIAS2}	Second Bias Set	Connect via resistor to a common V _{CC} . V _{BIAS2} and series resistor sets I _{CCQ3} . Setting V _{BIAS2} \leq 0.2 V will disable the final stage of the device.
14	V _{BIAS1}	First Bias Set	Connect via resistor to a common V _{CC} . V _{BIAS1} and series resistor set I _{CCQ1} and I _{CCQ2} . Setting V _{BIAS1} \leq 0.2 V will disable the 1st and 2nd stages of the device.
15	V _{CC1}	V _{CC} Bias Voltage	Connect to a common V _{CC} . Place bypass capacitors as close to the pin as possible.
PKG BASE	GND	Ground	Provides DC and RF ground for the amplifier, as well as thermal heat sink. Recommend multiple 8 mil vias beneath the package for optimal RF and thermal performance. Refer to evaluation board top layer graphic on the schematic page.

Absolute Ratings

Parameter	Symbol	Min.	Max.	Unit
Supply Voltage	V_{CC}	3	5.5	V
RF Input Power: Load VSWR $\leq 2:1$, all phase angles, $V_{CC} = 5$ V, CW Tone, 100% Duty Cycle, $T_{PKG\ BASE} = -40$ to 115 °C	$P_{IN\ MAX}$		23	dBm
Operating Temperature (Package Base)	$T_{PKG\ BASE}$	-40	115	°C
Maximum Junction Temperature (MTTF > 10^6 hours)	$T_J\ MAX$		190	°C
Maximum Dissipated Power Stage 1 (DC only, no RF applied)	$P_{DISS\ MAX}$		60	mW
Maximum Dissipated Power Stage 2 (DC only, no RF applied)	$P_{DISS\ MAX}$		190	mW
Maximum Dissipated Power Stage 3 (DC only, no RF applied)	$P_{DISS\ MAX}$		300	mW
Electrostatic Discharge				
Human Body Model	HBM	1000		V
Charged Device Model	CDM	750		V
Storage				
Storage Temperature	T_{STG}	-65	150	°C
Moisture Sensitivity Level	MSL		1	--


Caution! ESD Sensitive Device.
Exceeding Absolute Maximum Rating conditions may cause permanent damage.

Note: For additional information, please refer to [Manufacturing Note MN-001 - Packaging and Manufacturing Information](#).

All Guerrilla RF products are provided in RoHS compliant lead (Pb)-free packaging. For additional information, please refer to the [Certificate of RoHS Compliance](#).

Recommended Operating Conditions

Parameter	Symbol	Specification			Unit	Condition
		Min.	Typ.	Max.		
Supply Voltage	V_{CC}	3	5	5.5	V	
Operating Temperature (Package Base)	$T_{PKG\ BASE}$	-40		115	°C	
RF Frequency Range	F_{RF}	3.3		4.2	GHz	Notes 1 & 2.
RF_IN Port Impedance	Z_{RFIN}		50		Ω	
RF_OUT Port Impedance	Z_{RFOUT}		50		Ω	

Note 1: Operation outside of this range is supported by using different custom tunes. Examples of other optimized tunes can be found here: [GRF5236 Custom Tunes](#)

Note 2: Contact the Guerrilla RF Applications team for guidance on optimizing the tuning of the device for alternative bands.

Nominal Operating Parameters - General

The following conditions apply unless noted otherwise: typical application schematic using the 3.3 to 4.2 GHz tuning set. $R_{BIAS1} = 453 \Omega$ and $R_{BIAS2} = 2940 \Omega$, $V_{CC} = 5 \text{ V}$, 50Ω system impedance, $P_{OUT} = 4 \text{ dBm}$, $F_{TEST} = 3.8 \text{ GHz}$, $T_{PKG \text{ BASE}} = 25 \text{ }^{\circ}\text{C}$. Evaluation board losses are included within the specifications.

Parameter	Symbol	Specification			Unit	Condition
		Min.	Typ.	Max.		
V_{BIAS1} Logic Input Low	V_{IL}	0		0.2	V	Measured at V_{BIAS1} node (with bias-setting resistor in line between node and pin 14).
V_{BIAS1} Logic Input High	V_{IH}	1.5		V_{CC}	V	
V_{BIAS2} Logic Input Low	V_{IL}	0		0.2	V	Measured at V_{BIAS2} node (with bias-setting resistor in line between node and pin 13).
V_{BIAS2} Logic Input High	V_{IH}	1.5		V_{CC}	V	
V_{BIAS1} Logic Low Current	I_{IL}		20		nA	$V_{BIAS1} = 0.2 \text{ V}$.
V_{BIAS1} Logic High Current	I_{IH}		5.7		mA	$V_{BIAS1} = 5 \text{ V}$.
V_{BIAS2} Logic Low Current	I_{IL}		30		nA	$V_{BIAS2} = 0.2 \text{ V}$.
V_{BIAS2} Logic High Current	I_{IH}		0.7		mA	$V_{BIAS2} = 5 \text{ V}$.
Switching Rise Time	$t_{STBY-RISE}$		120		ns	Turn ON time: V_{BIAS1} & V_{BIAS2} LOW to HIGH (note 2) .
Switching Fall Time	$t_{STBY-FALL}$		15		ns	Turn OFF time: V_{BIAS1} & V_{BIAS2} HIGH to LOW (note 3) .

Note 2: Switching Time: 50% of V_{BIAS} to 90% of P_{OUT} .

Note 3: Switching Time: 50% of V_{BIAS} to 10% of P_{OUT} .

Disabled Mode

Parameter	Symbol	Specification			Unit	Condition
		Min.	Typ.	Max.		
Standby Current	I_{STBY}		145		nA	$V_{CC} = 5 \text{ V}$. $V_{BIAS1} = V_{BIAS2} = 0.2 \text{ V}$.

Nominal Operating Parameters - General (continued)

Thermal Data

Parameter	Symbol	Specification			Unit	Condition
		Min.	Typ.	Max.		
Thermal Resistance (Infrared Scan)	Θ_{JC}		71		°C/W	On standard evaluation board.
Junction Temperature @ 115 °C reference (package Heat Sink)	T _{JUNCTION}		171		°C	V _{CC} = 5 V. I _{CCQ} = 115 mA. P _{DISS} = 600 mW. No RF applied (note 4).

Note 4: MTTF > 10⁶ hours for T_{JUNCTION} ≤ 190 °C.

Nominal Operating Parameters - RF

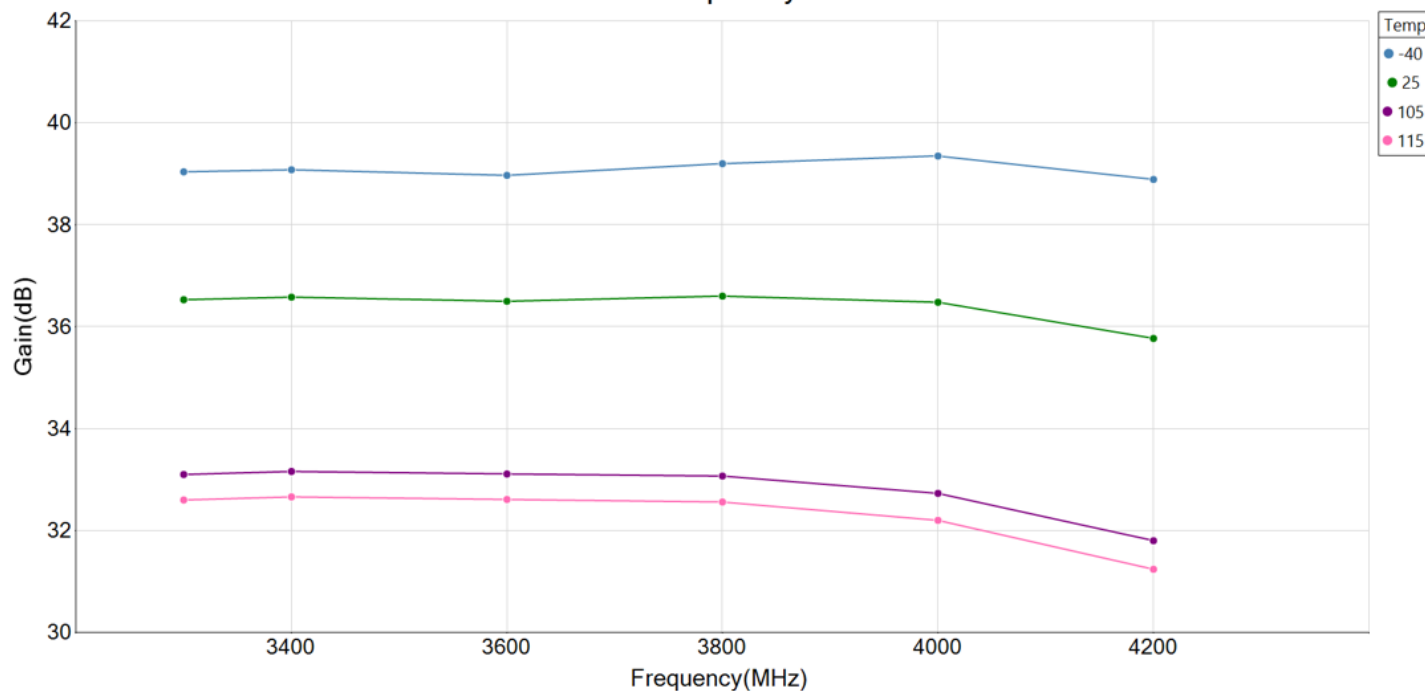
3.3 to 4.2 GHz, 5 V Supply

The following conditions apply unless noted otherwise: typical application schematic using the 3.3 to 4.2 GHz tuning set, $V_{CC} = 5\text{ V}$, $R_{BIAS1} = 453\ \Omega$ and $R_{BIAS2} = 2940\ \Omega$, $F_{TEST} = 3.8\text{ GHz}$, $50\ \Omega$ system impedance, $T_{PKG\ BASE} = 25\ ^\circ\text{C}$. Evaluation board losses are included within the specifications.

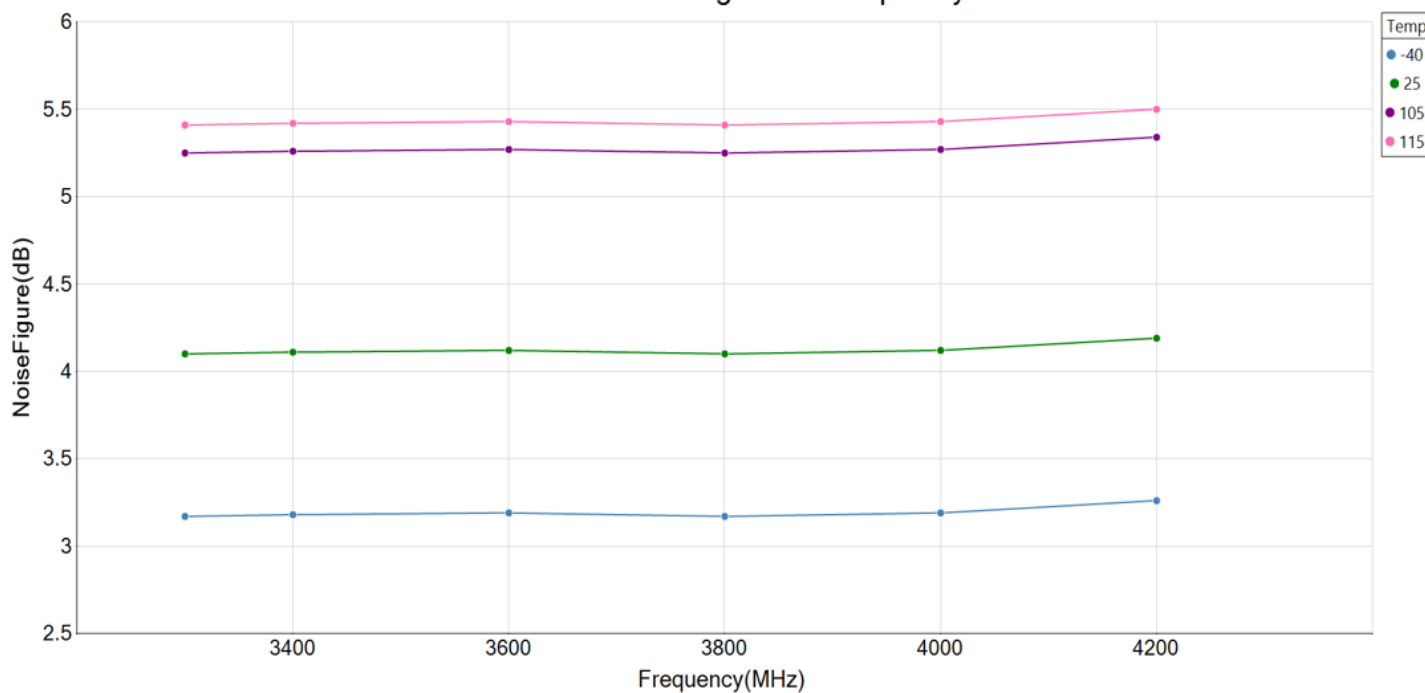
Parameter	Symbol	Specification			Unit	Condition
		Min.	Typ.	Max.		
Supply Quiescent Current	I_{CCQ}		95		mA	
Supply Current with RF Applied	I_{CC}		116		mA	$P_{OUT} = 14\text{ dBm}$.
Gain	S_{21}		36.7		dB	
Gain Flatness	$S_{21_{FLAT}}$		0.8		dB	$F_{RF} = 3.3\text{ to }4.2\text{ GHz}$
Standby Mode Gain	$S_{21_{STBY}}$		-46		dB	$V_{BIAS1} < 0.2\text{ V}$, $V_{BIAS2} < 0.2\text{ V}$.
Input Return Loss	S_{11}		-13		dB	
Output Return Loss	S_{22}		-3.4		dB	
Reverse Isolation	S_{12}		-48		dB	
Evaluation Board Noise Figure	NF		4.1		dB	
Output 3rd Order Intercept Point	OIP3		33.8		dBm	4 dBm P_{OUT} per tone at 2 MHz spacing.
Output 1 dB Compression Power	OP1dB		30.1		dBm	

GRF5236 Typical Operating Curves: 3.3 - 4.2 GHz Tune, 5 V

GRF5236 Gain vs Frequency at Pin = -25 dBm

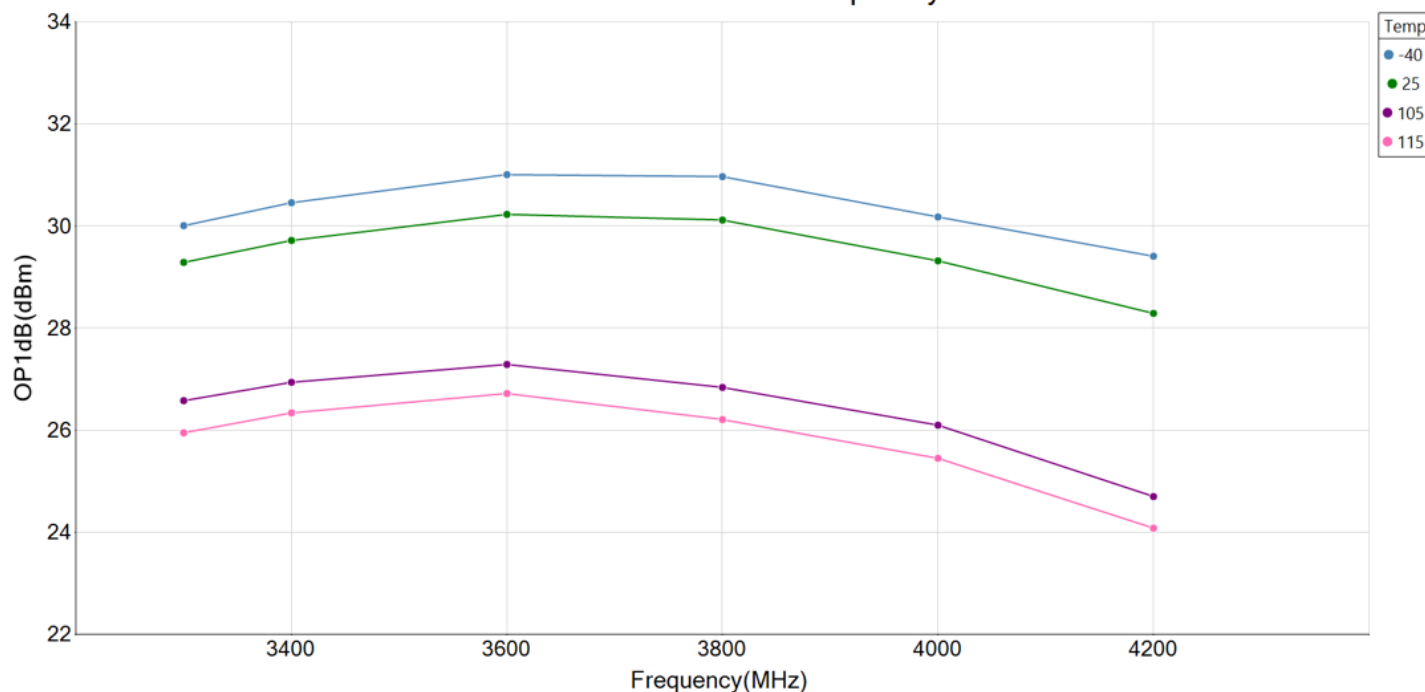


GRF5236 Noise Figure vs Frequency

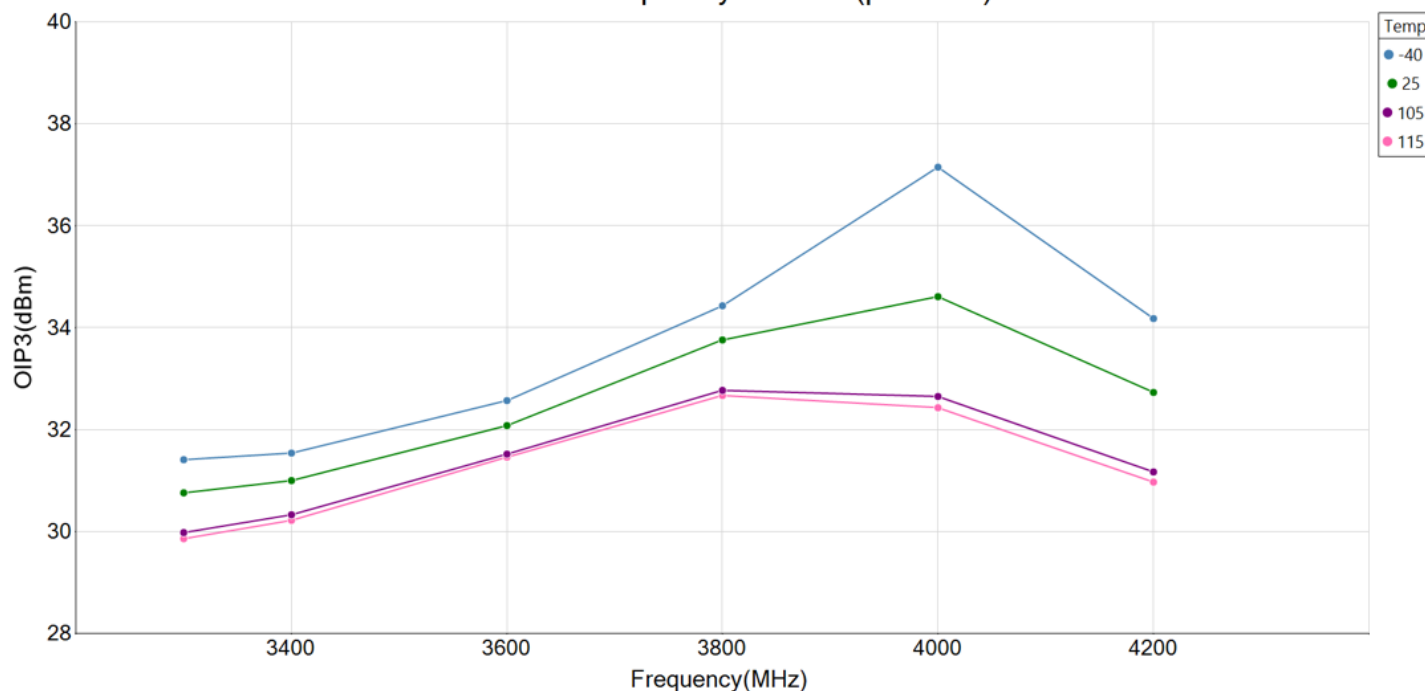


GRF5236 Typical Operating Curves: 3.3 - 4.2 GHz Tune, 5 V

GRF5236 OP1dB vs Frequency

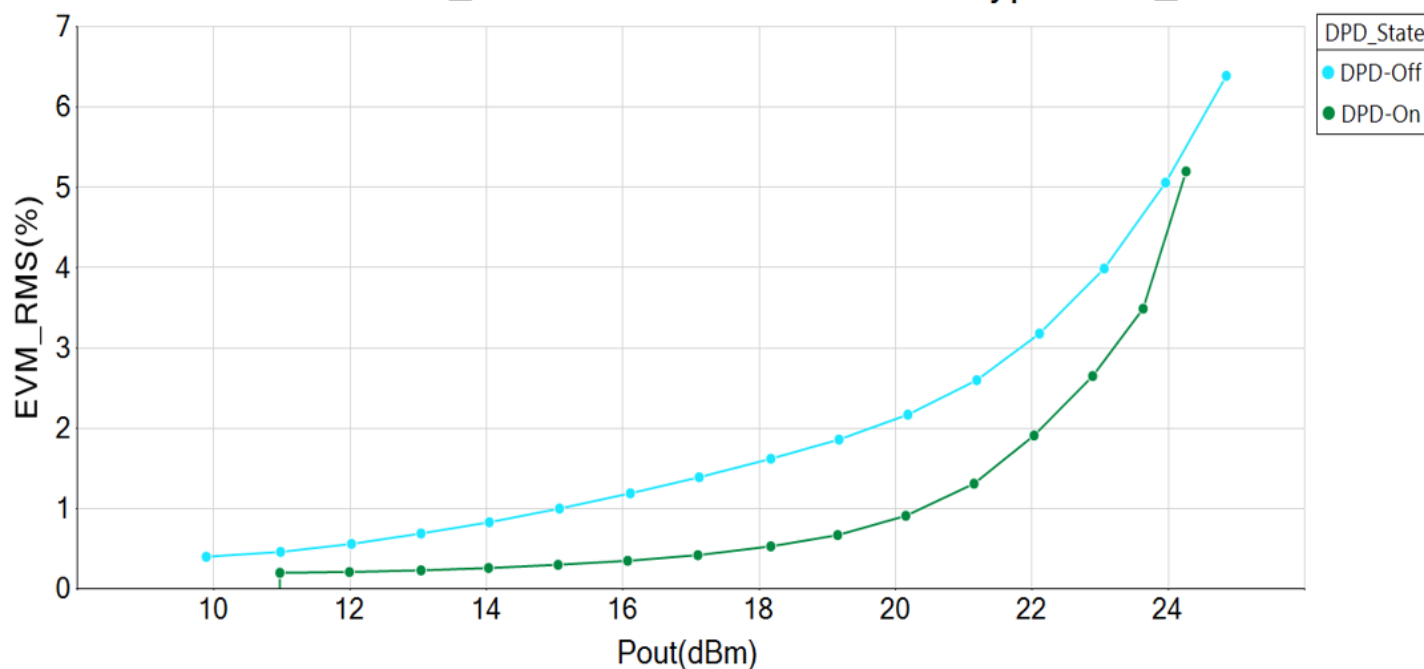


GRF5236 OIP3 vs Frequency at Pout (per tone) = 4 dBm

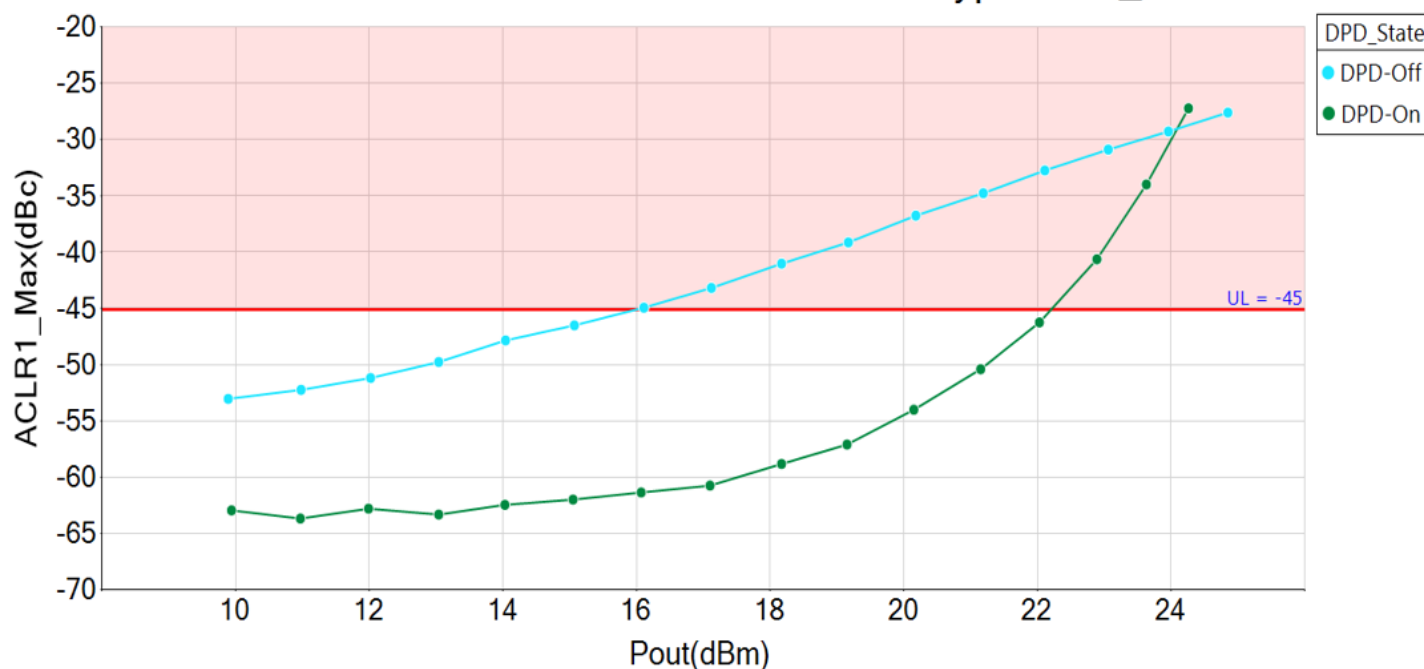


GRF5236 Typical Operating Curves: 3.3 - 4.2 GHz Tune, 5 V, $F_{RF} = 3800$ MHz

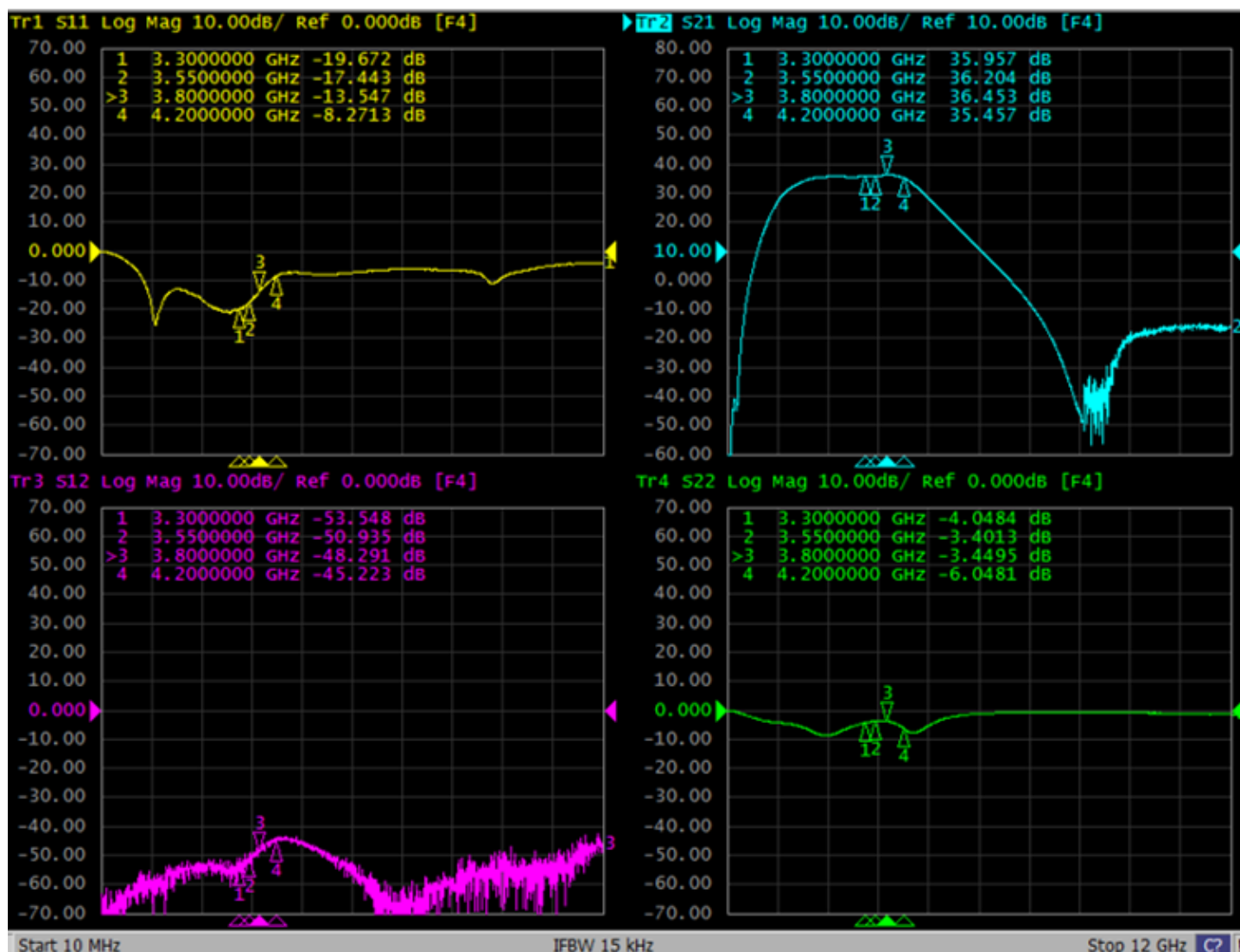
GRF5236 EVM_RMS vs Pout at ModulationType = 5G_10M



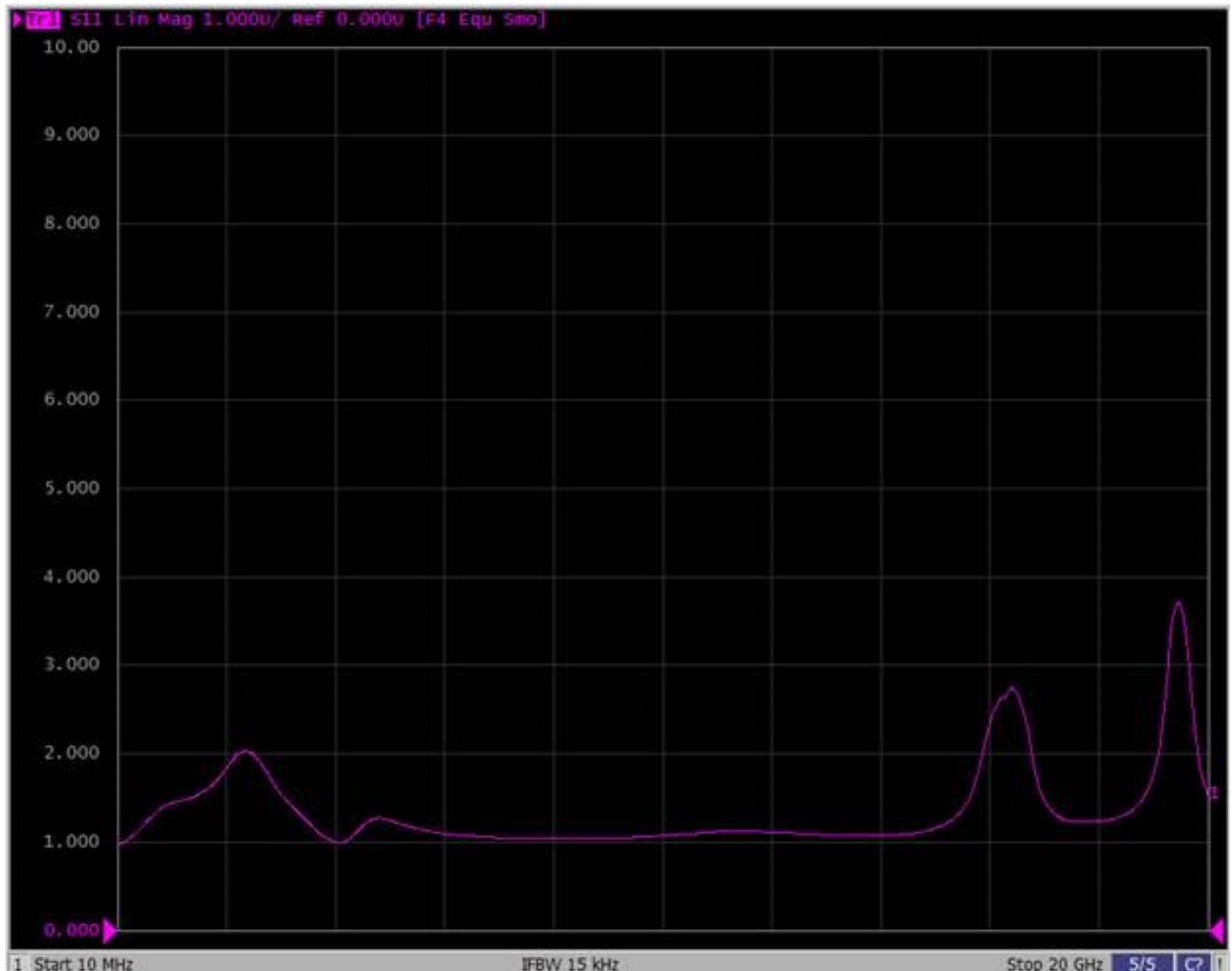
GRF5236 ACLR1 vs Pout at ModulationType = 5G_10M



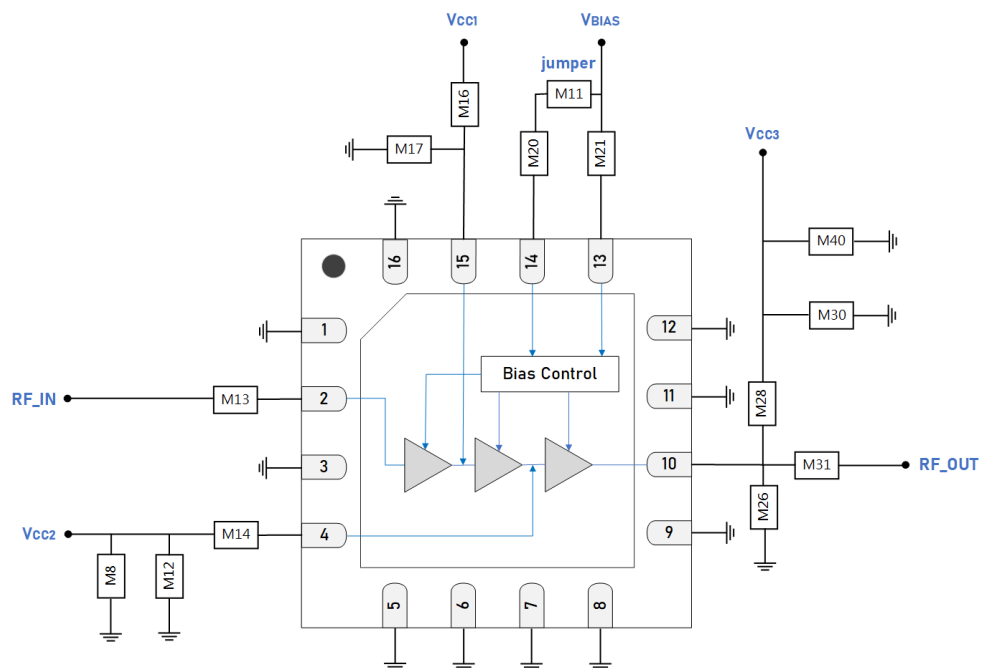
GRF5236 Typical Operating Curves: S-Parameters (3.3 - 4.2 GHz Tune, 5 V)



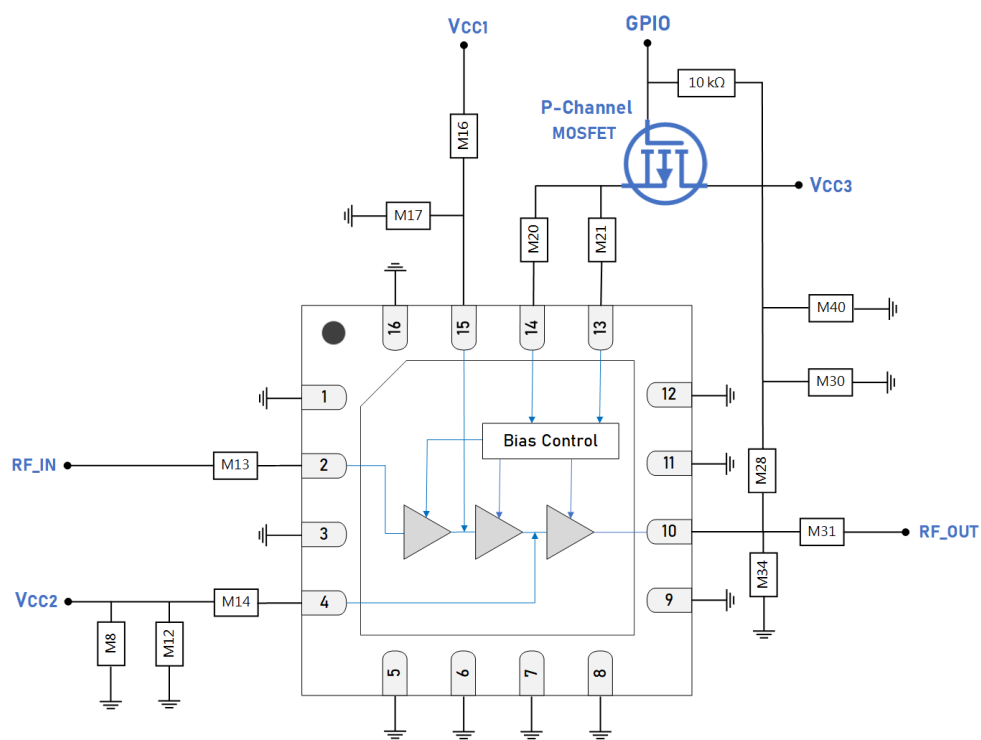
GRF5236 Typical Operating Curves: Stability Mu Factor (10 MHz - 20 GHz)



Note: Mu factor ≥ 1.0 implies unconditional stability.

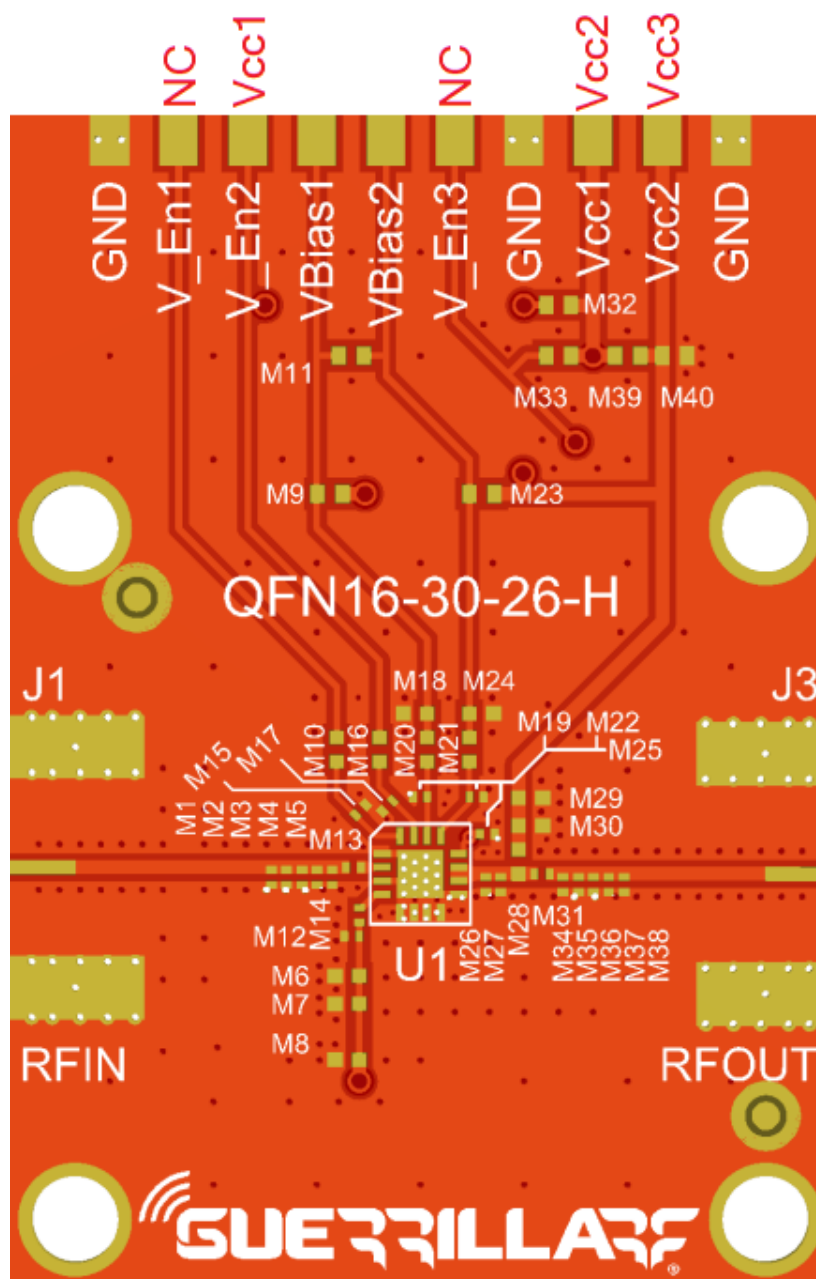


GRF5236 Standard Evaluation Board Schematic



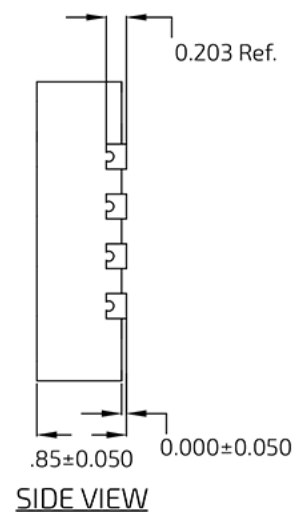
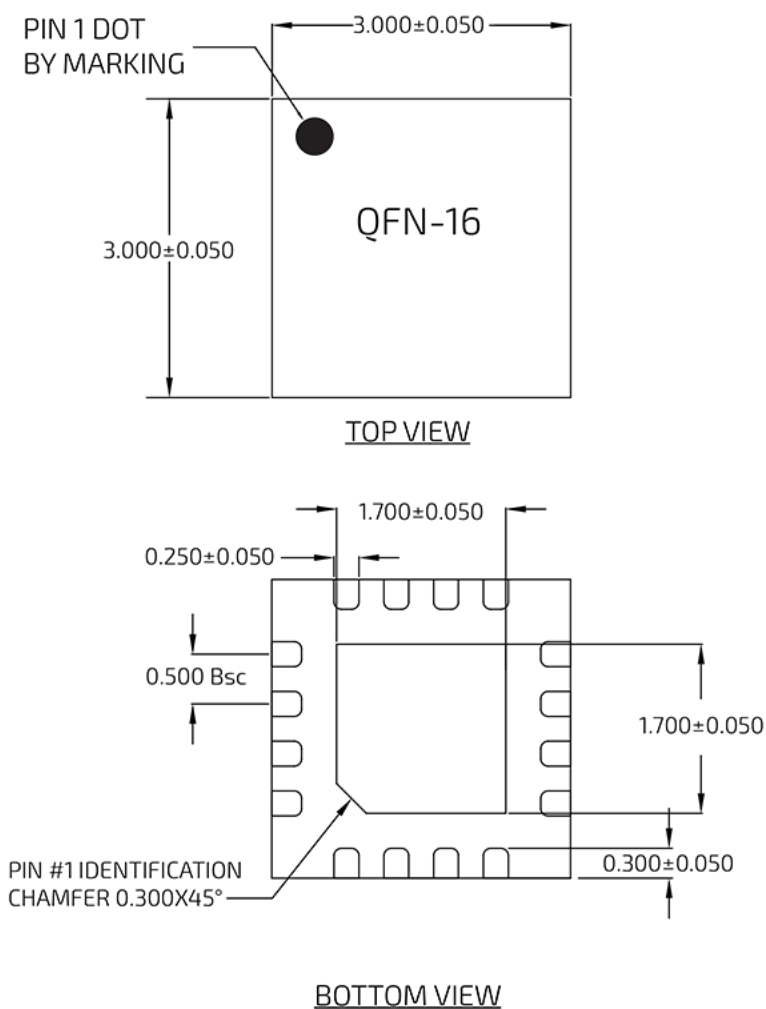
GRF5236 Recommended Schematic for applications using low current GPIO to toggle V_{BIAS1} and V_{BIAS2}

GRF5236 Evaluation Board Assembly Diagram

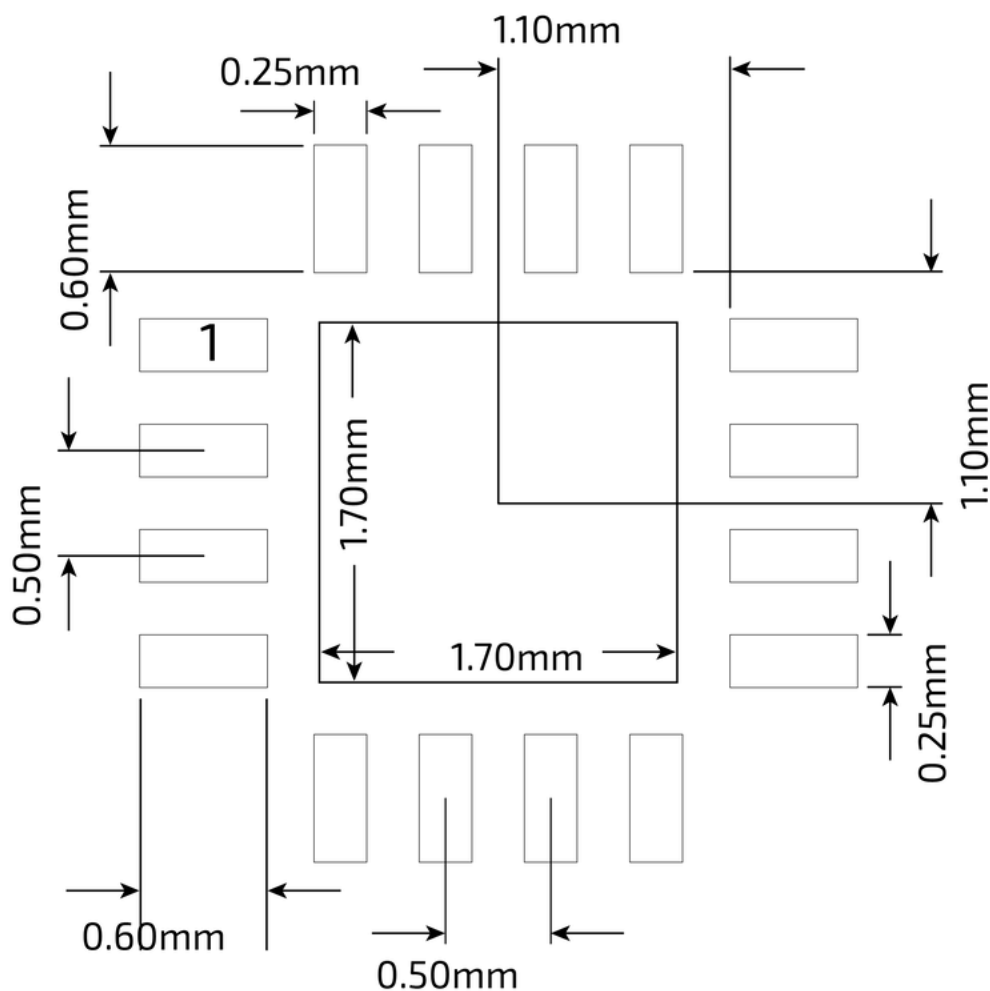


GRF5236 Evaluation Board Assembly Diagram Reference: 3.3 - 4.2 GHz Tune

Component	Type	Manufacturer	Family	Value	Package Size	Substitution
M8	Capacitor	Murata	GRM	10 μ F	0402	ok
M11	Resistor (jumper)	Various	5%	0 Ω	0402	ok
M12	Capacitor	Murata	GRM	0.1 μ F	0201	ok
M13	Resistor	Various	5%	0 Ω	0402	ok
M14	Inductor	Murata	LQPTN	6.2 nH	0201	ok
M16	Resistor	Various	5%	0 Ω	0402	ok
M17	Capacitor	Murata	GRM	0.1 μ F	0201	ok
M20	Resistor	Various	5%	453 Ω	0402	ok
M21	Resistor	Various	5%	2940 Ω	0402	ok
M26	Capacitor	Murata	GJM	1.2 pF	0201	ok
M28	Inductor	Murata	LQW	6.2 nH	0402	ok
M30	Capacitor	Murata	GRM	0.1 μ F	0402	ok
M31	Capacitor	Murata	GJM	5.1 pF	0201	ok
M40	Capacitor	Murata	GRM	10 μ F	0402	
Evaluation Board	QFN16-30-26-H					



QFN 16 3x3mm Package Dimensions



QFN 16 3x3mm Suggested PCB Footprint (Top View)

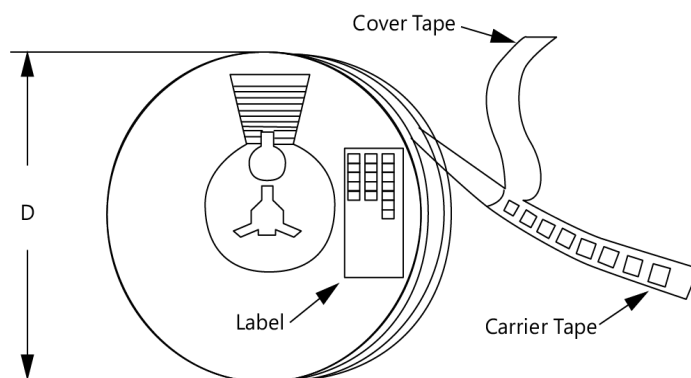
Package Marking Diagram



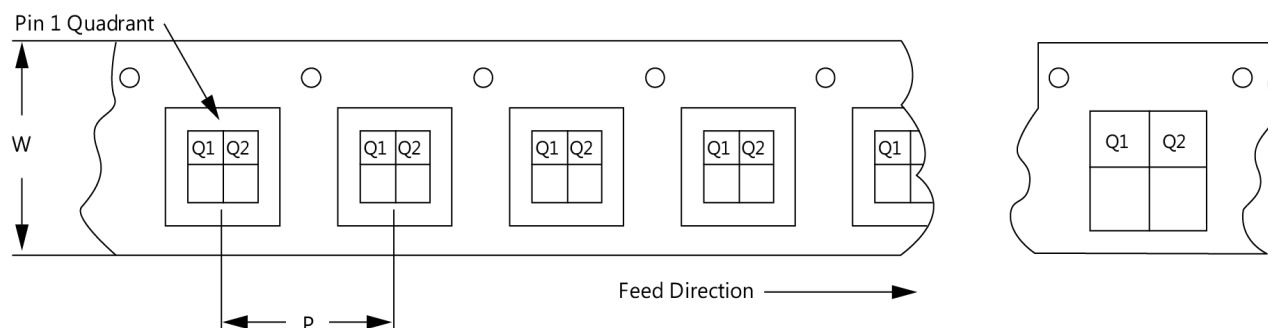
Line 1: "YY" = Year. "WW" = WORK WEEK the Device was assembled.
 Line 2: "GRF" = Guerrilla RF
 Line 3: "XXXX" = Device Part Number.

Tape and Reel Information

Guerrilla RF's tape and reel specification complies with Electronics Industries Association (EIA) standards for "Embossed Carrier Tape of Surface Mount Components for Automatic Handling" (reference EIA-481). Devices are loaded with pins down into the carrier pocket with protective cover tape and reeled onto a plastic reel. Each reel is packaged in a cardboard box. There are product labels on the reel, the protective ESD bag, and the outside surface of the box. For the latest reel specifications and package information (including units/reel), please visit [Package Manufacturing Information](#) | [Guerrilla RF](#) (guerrilla-rf.com).



Tape and Reel Packaging with Reel Diameter Noted (D)



Carrier Tape Width (W), Pitch (P), Feed Direction and Pin 1 Quadrant Information



Revision History

Revision Date	Description of Change
February 19, 2024	Advance Data Sheet.
May 31, 2024	Preliminary Data Sheet.
October 17, 2024	Header Frequency Range: Lowered low end of Frequency Range from 3.3 to 3.1 GHz.
June 4, 2025	Release Ø Data Sheet.



Data Sheet Classifications

Data Sheet Status	Notes
Advance	S-parameter and NF data based on EM simulations for the fully packaged device using foundry-supplied transistor S-parameters. Linearity estimates based on device size, bias condition and experience with related devices.
Preliminary	All data based on evaluation board measurements taken within the Guerrilla RF Applications Lab. Any MIN/MAX limits represented within the data sheet are based solely on <i>estimated</i> part-to-part variations and process spreads. All parametric values are subject to change pending the collection of additional data.
Release Ø	All data based on measurements taken with <i>production-released</i> material. TYP values are based on a combination of ATE and bench-level measurements, with MIN/MAX limits defined using <i>modelled estimates</i> that account for part-to-part variations and expected process spreads. Although unlikely, future refinements to the TYP/MIN/MAX values may be in order as multiple lots are processed through the factory.
Release A-Z	All data based on measurements taken with production-released material <i>derived from multiple lots which have been fabricated over an extended period of time</i> . MIN/MAX limits may be refined over previous releases as more statistically significant data is collected to account for process spreads.

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